

PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q74738

Chen Fung LENG, et al.

Appln. No.: 10/552,046

Group Art Unit: 2812

Confirmation No.: 6904

Examiner: unknown

Filed: January 9, 2007

For: MULTI-CHIP BALL GRID ARRAY PACKAGE AND METHOD OF MANUFACTURE

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

ATTN: Office of Initial Patent Examination
Filing Receipt Correction
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and request the following correction:

Assignment For Published Patent Application: United Test and Assembly Center Ltd. And

Infineon Technologies

REQUEST FOR CORRECTED OFR
U.S. Appln. No.: 10/552,046

Attorney Docket No.: Q74738

Verification for the requested correction is indicated on the Assignment filed January 30,
2007.

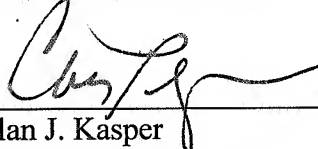
SUGHRUE MION, PLLC
Telephone: (202) 293-7060
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WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Respectfully submitted,

 #40,766
Alan J. Kasper
Registration No. 25,426



Date: June 22, 2007



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
 United States Patent and Trademark Office
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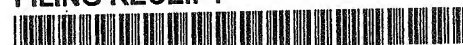
APPL NO.	FILING OR 371(c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	TOT CLMS	IND CLMS
10/552,046	01/09/2007	2812	1030	Q74738	9	2

23373
 SUGHRUE MION, PLLC
 2100 PENNSYLVANIA AVENUE, N.W.
 SUITE 800
 WASHINGTON, DC 20037



CONFIRMATION NO. 6904

FILING RECEIPT



OC000000023205500

Date Mailed: 04/02/2007

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Fung Leng Chen, Singapore, SINGAPORE;
 Seong Kwang Brandon Kim, Singapore, SINGAPORE;
 Wee Lim Cha, Singapore, SINGAPORE;
 Yi-Sheng Anthony Sun, Singapore, SINGAPORE;
 Wolfgang Hetzel, Natheim, GERMANY;
 Jochen Thomas, Munich, GERMANY;

Assignment For Published Patent Application: United Test and Assembly Center Ltd. and Infineon Technologies

Power of Attorney: The patent practitioners associated with Customer Number 23373.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/IB04/01734 04/02/2004

Foreign Applications

If Required, Foreign Filing License Granted: 03/31/2007

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/552,046**

Projected Publication Date: 07/12/2007

Non-Publication Request: No

Early Publication Request: No

Title

Multi-chip ball grid array package and method of manufacture

Preliminary Class

438

PROTECTING YOUR INVENTION OUTSIDE THE UNITED STATES

Since the rights granted by a U.S. patent extend only throughout the territory of the United States and have no effect in a foreign country, an inventor who wishes patent protection in another country must apply for a patent in a specific country or in regional patent offices. Applicants may wish to consider the filing of an international application under the Patent Cooperation Treaty (PCT). An international (PCT) application generally has the same effect as a regular national patent application in each PCT-member country. The PCT process **simplifies** the filing of patent applications on the same invention in member countries, but **does not result** in a grant of "an international patent" and does not eliminate the need of applicants to file additional documents and fees in countries where patent protection is desired.

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Applicants may wish to consult the USPTO booklet, "General Information Concerning Patents" (specifically, the section entitled "Treaties and Foreign Patents") for more information on timeframes and deadlines for filing foreign patent applications. The guide is available either by contacting the USPTO Contact Center at 800-786-9199, or it can be viewed on the USPTO website at <http://www.uspto.gov/web/offices/pac/doc/general/index.html>.

For information on preventing theft of your intellectual property (patents, trademarks and copyrights), you may wish to consult the U.S. Government website, <http://www.stopfakes.gov>. Part of a Department of Commerce initiative, this website includes self-help "toolkits" giving innovators guidance on how to protect intellectual property in specific countries such as China, Korea and Mexico. For questions regarding patent enforcement issues, applicants may call the U.S. Government hotline at 1-866-999-HALT (1-866-999-4158).

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ASSIGNMENT

WHEREAS:

- Fung Leng CHEN, Singapore
- Seong Kwang Brandon KIM, South Korea
- Wee Lim CHA, Singapore
- Yi-Sheng Anthony SUN, Taiwan

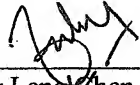
hereinafter called "Assignors", are employees of United Test and Assembly Center Ltd. and have invented, together with Wolfgang Hetzel and Jochen Thomas of Germany, employees of INFINEON TECHNOLOGIES, the invention as disclosed and claimed in the following U.S. provisional application:

60/459,353, hereinafter called "the '353 provisional application", filed April 2, 2003, entitled **"MULTI-CHIP BALL GRID ARRAY PACKAGE AND METHOD OF MANUFACTURE"** naming the above individuals as inventors; and

Whereas, UNITED TEST AND ASSEMBLY CENTER LTD., hereinafter called "Assignee", desires to acquire the entire right, title, and interest in the application and invention disclosed and claimed therein and in any Letters Patent issuing thereon, or issuing on any subsequently filed United States patent applications which claim the benefit of the '353 provisional application's filing date;

NOW, THEREFORE, for One Dollar (\$1.00) and other valuable consideration, receipt whereof is hereby acknowledged,

We, the above named Assignors, hereby sell, assign and transfer to the above named Assignee, its successors and assigns, nunc pro tunc as of April 2, 2004, the entire right, title and interest in the application and the invention disclosed therein for the United States of America and all countries foreign thereto, including rights of priority under the International Convention of Paris (1883) as amended, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in the application to the Assignee, its successors and assigns; and we hereby agree that the Assignee may apply for foreign Letters Patent on the invention and we will execute without further consideration all papers deemed necessary by the Assignee in connection with the United States and foreign applications when called upon to do so by the Assignee.

Date: June 24th 2004 s/  _____
Fung Leng Chen

Date: June 24th 2004 s/  _____
Seong Kwang Brandon Kim

Date: 24th June 2004 s/  _____
Wee Lim Cha

Date: 24th June 2004 s/  _____
Yi-Sheng Anthony Sun

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

ASSIGNMENT

WHEREAS:

- Wolfgang HETZEL, Germany
- Jochen THOMAS, Germany

hereinafter called "Assignors", are employees of INFINEON TECHNOLOGIES, and have invented, together with Fung Leng Chen, Seong Kwang Brandon Kim, Wee Lim Cha and Yi-Sheng Anthony Sun of Singapore, employees of United Test and Assembly Center, Ltd., the invention as disclosed and claimed in the following U.S. provisional application:

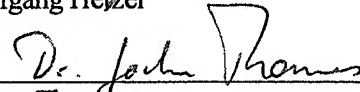
60/459,353, hereinafter called "the '353 provisional application", filed April 2, 2003, entitled **"MULTI-CHIP BALL GRID ARRAY PACKAGE AND METHOD OF MANUFACTURE"** naming the above individuals as inventors; and

Whereas, INFINEON TECHNOLOGIES, hereinafter called "Assignee", desires to acquire the entire right, title, and interest in the application and invention disclosed and claimed therein and in any Letters Patent issuing thereon, or issuing on any subsequently filed United States patent applications which claim the benefit of the '353 provisional application's filing date;

NOW, THEREFORE, for One Dollar (\$1.00) and other valuable consideration, receipt whereof is hereby acknowledged,

We, the above named Assignors, hereby sell, assign and transfer to the above named Assignee, its successors and assigns, nunc pro tunc as of April 2, 2004, the entire right, title and interest in the application and the invention disclosed therein for the United States of America and all countries foreign thereto, including rights of priority under the International Convention of Paris (1883) as amended, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in the application to the Assignee, its successors and assigns; and we hereby agree that the Assignee may apply for foreign Letters Patent on the invention and we will execute without further consideration all papers deemed necessary by the Assignee in connection with the United States and foreign applications when called upon to do so by the Assignee.

Date: 12/26/2004 s/ 
Wolfgang Hetzel

Date: 14/July/2004 s/ 
Jochen Thomas

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)